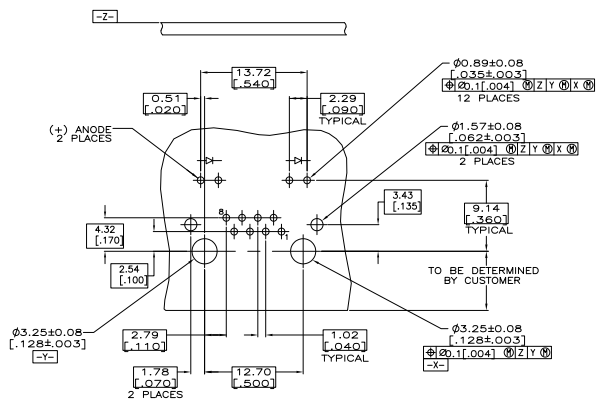


- MATERIAL:
 HOUSING - HIGH TEMPERATURE THERMOPLASTIC, BLACK, UL94V-0.
 TERMINALS - 0.36[.014] THICK PHOS BRONZE PLATED WITH 3.81µm[.000150] MINIMUM THICK BRIGHT TIN LEAD IN SOLDER AREA. 1.27µm[.000050] MINIMUM GOLD IN LOCALIZED PLATE AREA. ENTIRE TERMINAL PLATED WITH 1.27µm[.000050] MINIMUM THICK NICKEL.
 SHIELD - 0.19[.007] THICK COPPER ZINC ALLOY PREPLATED WITH 1.27µm[.000050] MINIMUM SATIN NICKEL WITH 2.03µm[.000080] MINIMUM TIN POST DIPPED ON PCB GROUND TABS.
 LIGHT EMITTING DIODE (LED) - DIFFUSED EPOXY LENS, 0.51 x 0.51[.020 x .020] CARBON STEEL (WIREFRAME LEADS) PREPLATED WITH 8.89µm[.000350] THICK TIN/COPPER OVER 2.03µm[.000080] THICK SILVER OVER 1.02µm[.000040] THICK COPPER OVER 3.56µm[.000140] THICK NICKEL OVER 1.02µm[.000040] THICK COPPER UNDERPLATE.
- JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68, SUBPART F.
- SUGGESTED PANEL OPENING DIMENSIONS.
- SUGGESTED CLEARANCE BETWEEN TOP OF CONNECTOR AND TOP PANEL OPENING.
- 0.051[.002] WHITE POLYESTER INSULATOR APPLIED TO BACK OF HOUSING.
- SEE TABLE FOR COLOR OF LEADS AND NUMBER REQUIRED.
- THIS MODULAR JACK WITH INTEGRATED LED IS NOT IR REFLOW SOLDERING PROCESS COMPATIBLE.



SUGGESTED PRINTED CIRCUIT BOARD LAYOUT (COMPONENT SIDE)

GREEN	GREEN	1116173-5
GREEN	YELLOW	1116173-4
YELLOW	GREEN	1116173-1
POSITION 2	POSITION 1	PART NUMBER
INDICATOR COLOR		

THIS DRAWING IS A CONTROLLED DOCUMENT.		DESIGNED BY	STYLUS	DATE	11-14-2154	REVISION NO.	1	REVISED TO	
INCHES	MM (INCHES)	DESIGNED BY	STYLUS	DATE	11-14-2154	REVISION NO.	1	REVISED TO	
DRAWING NO.		108-1163-4	TITLE		INVERTED MODULAR JACK ASSEMBLY, 1X1, SHIELDED, PANEL GROUND, LED, INSULATOR				
DRAWING NO.		114-2154	DATE		11-14-2154	REVISION NO.	1	REVISED TO	
DRAWING NO.		114-2154	DATE		11-14-2154	REVISION NO.	1	REVISED TO	
DRAWING NO.		114-2154	DATE		11-14-2154	REVISION NO.	1	REVISED TO	